

FIG. 1 (a)

Fig. 1 (b)
prior art

WTEE CONNECT METAL (3) PLATING MEMOCANE + (7) INSULATING FILM (OPTIONAL) (
INTERIORNAT OF FOLYIMIDE

(MT. PY. Au)

To PY. Au)

metal band (7a)

(Solder dam)

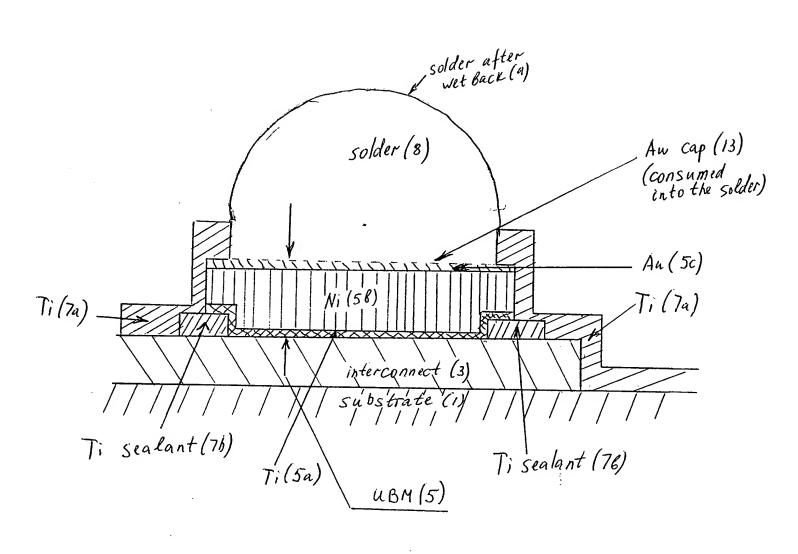
interconnect metal (3)

solder bump

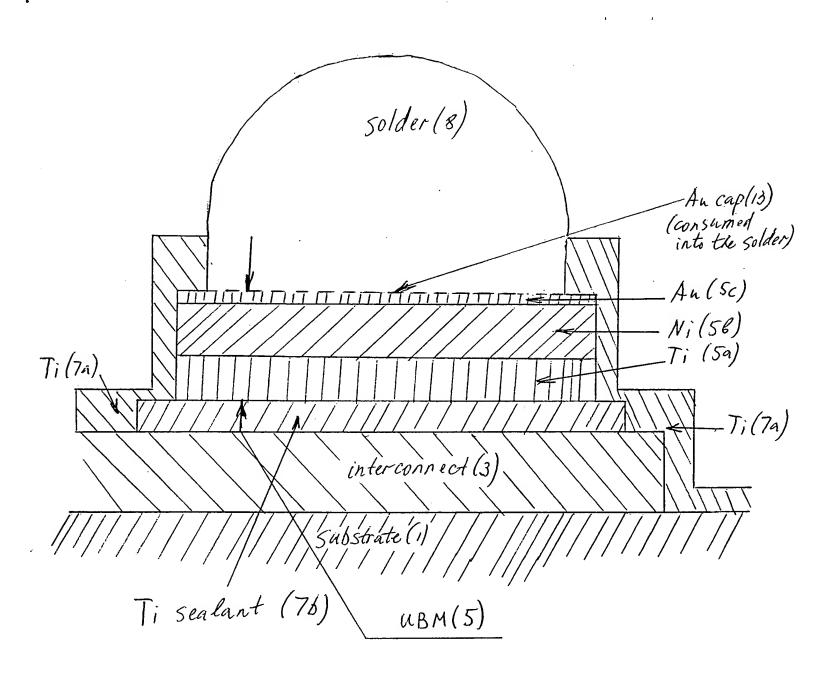
after heating /wet back (9)

Fig 2(a)

Fig. 2(6)



Fif. 3



Fi6 3 (a)

FIE 3(8)

solder (8) solder westable cap layer (Sc) diffusion barrier loyer (Sb) -adhesion improvement layer (Sa) UBM (5 interconnect (3) substrate, (1) plating membrane and non wettable dam (7) Fig. 4 Cr (plating membrane 7) Fig. 4(a) ETil plating membrane (7) Fig 4(8) 1/////= Cr. 7 plating membrane (7) Fig 4(c) Oxidizels; 1 plating
1 membrane
(7) (=Ti ) plating membrane (7) Fig 4(d)